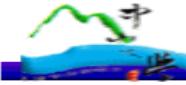


MBE and the low temperature, high magnetic field systems

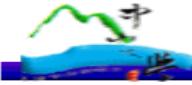
報告人:蔡振凱

指導教授:羅奕凱



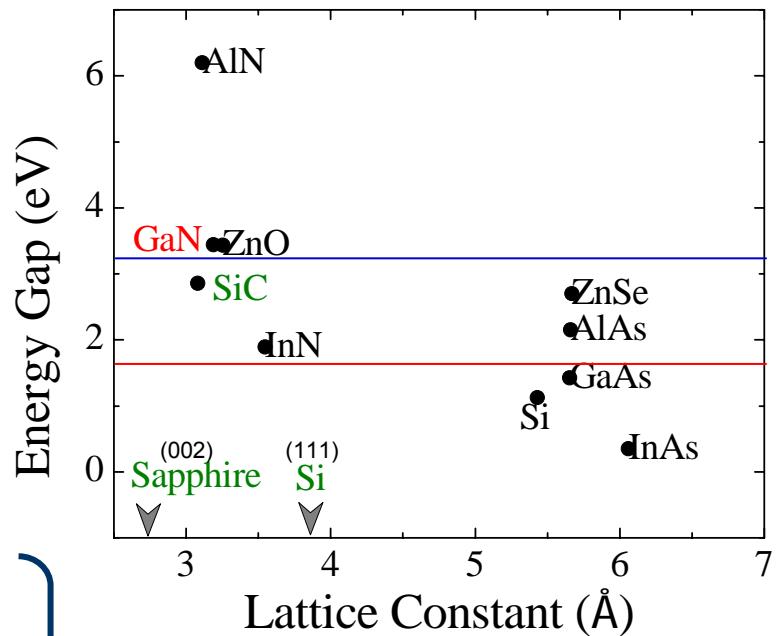
Outline

- Introduction
- RF Plasma assisted MBE system
- Hall effect measurement system
- Low temperature and high magnetic field system I—Lake shore 9705
- Low temperature and high magnetic field system II—Oxford
- Other equipments

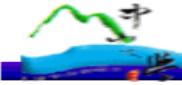


Introduction

- Energy gap
 - AlN: 6.2 eV (200 nm)
 - GaN: 3.44 eV (360 nm)
 - InN: 1.89 eV (656 nm)
(0.7-1.0 eV, Matsuoka *et al.*, APL 2002)
- Applications
 - Optoelectronic devices
 - solar blind and visible detectors
 - blue-ultraviolet light emitters
 - optical data storage
 - Electronic devices

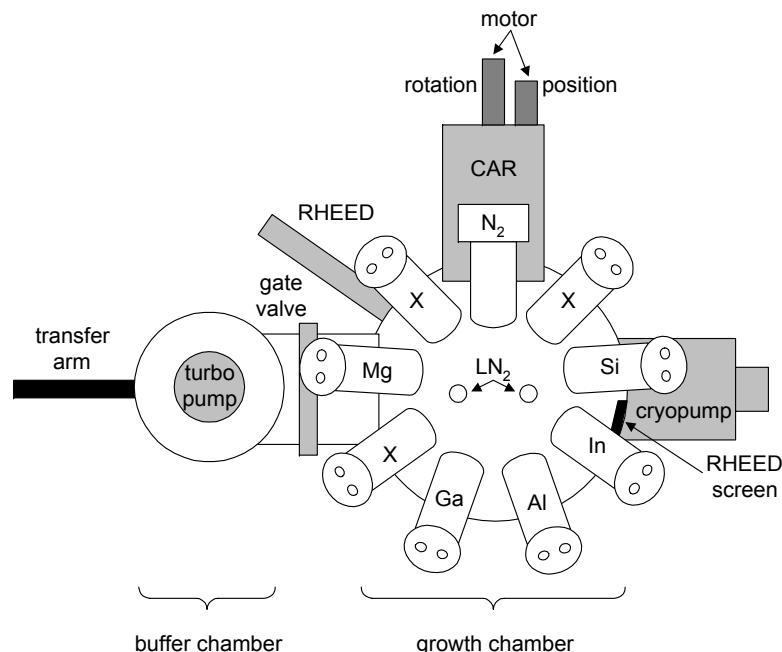


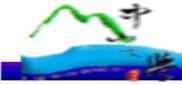
High power
High frequency
High temperature



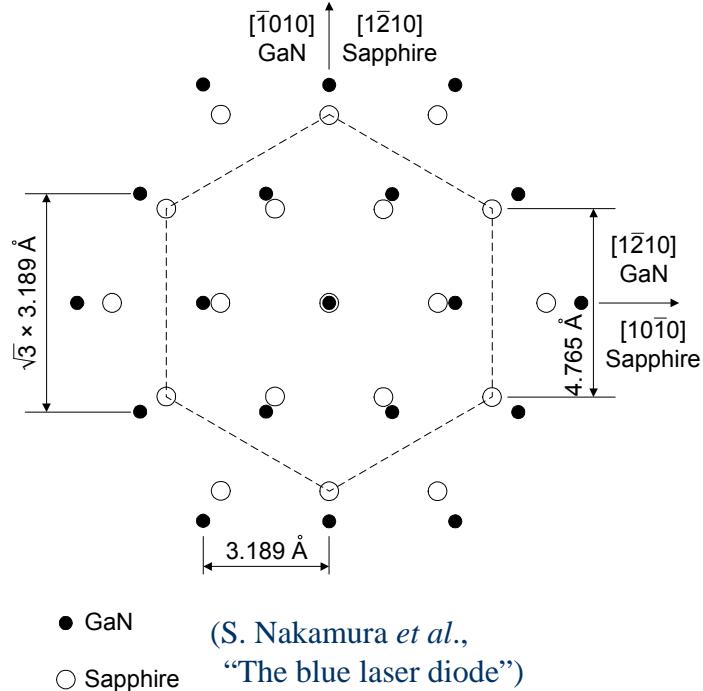
RF Plasma assisted MBE system

Applied EPI 930

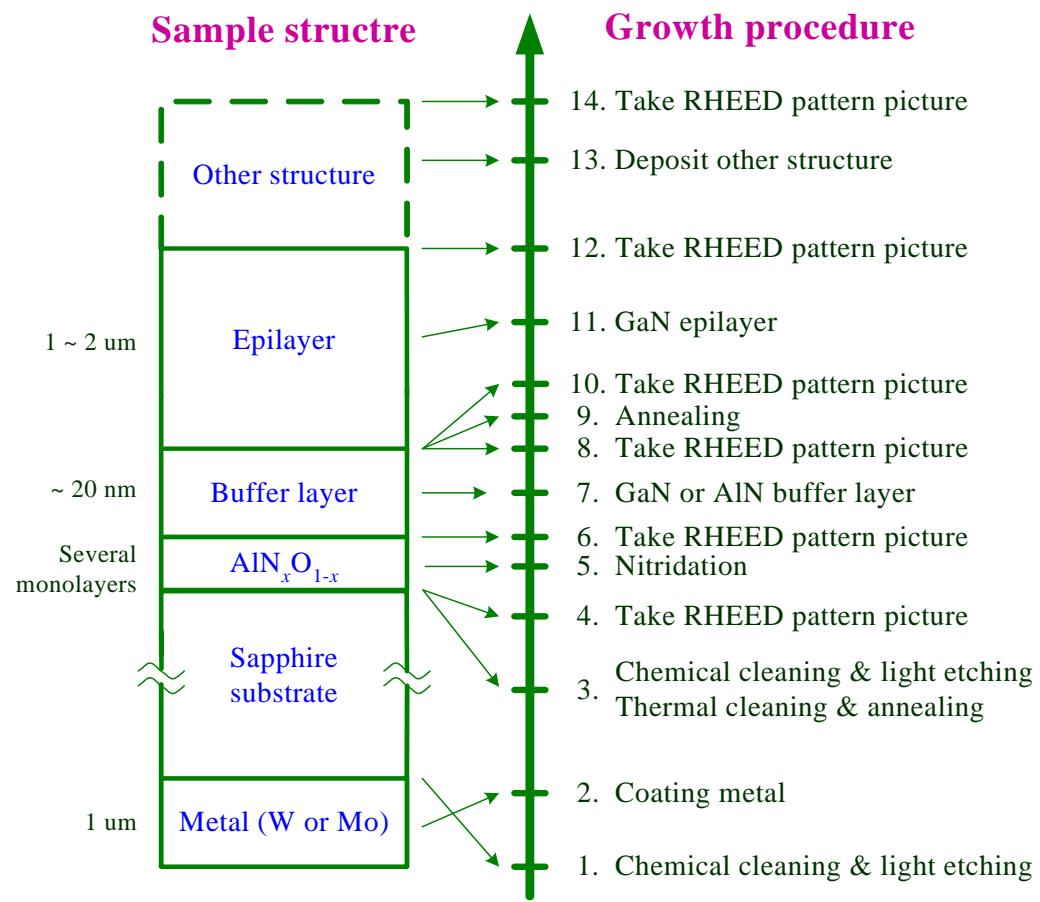


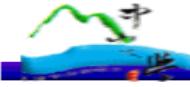


Growth procedures



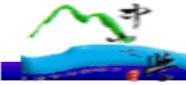
Lattice mismatch=16%
(GaN/sapphire)



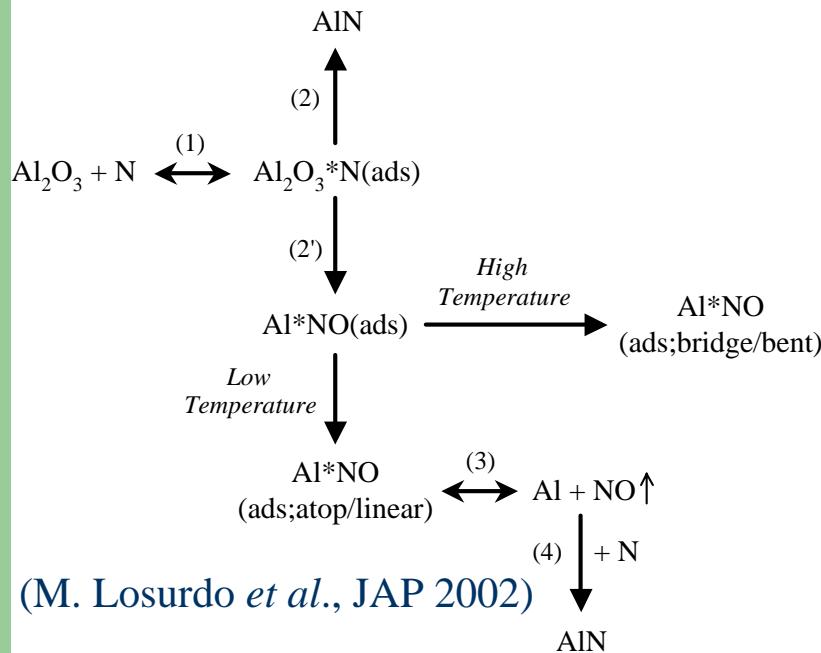


Growth conditions

- Nitridation
 - Substrate temperature, RF plasma power, N_2 flux, time
- GaN or AlN buffer layer
 - Substrate temperature, RF plasma power, N_2 flux, Ga(Al) flux, N/Ga(Al) ratio, thickness
- GaN epilayer
 - Substrate temperature, RF plasma power, N_2 flux, Ga flux, N/Ga ratio, thickness



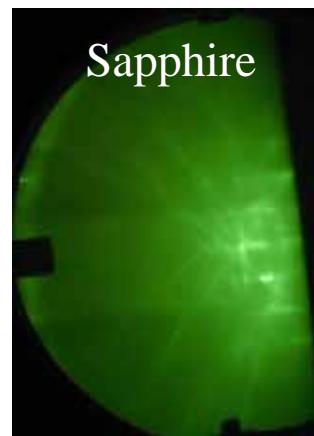
Nitridation



Lattice mismatch=2~3%

(GaN/AlN)

- (1) Adsorption equilibrium and in-diffusion of N atoms
- (2) Reactive step on an Al site
- (2') Reactive step on an O site
- (3) Adsorption/desorption equilibrium of NO in the top configuration
- (4) Further reaction on Al-site at low temperature

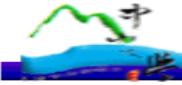


Sapphire

RHEED

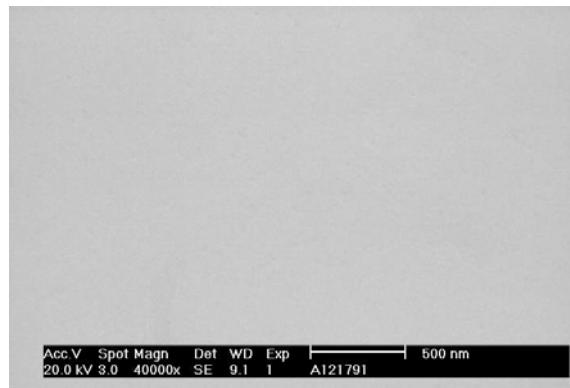
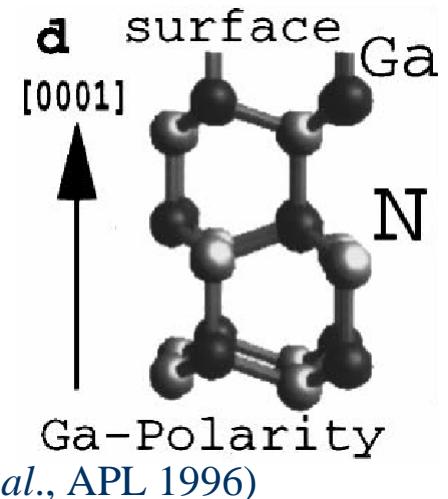
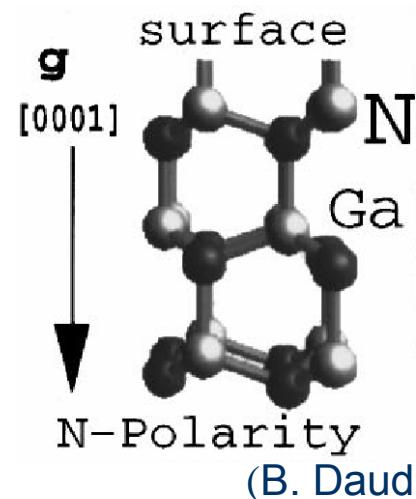
$[1\bar{1}\bar{2}0]$



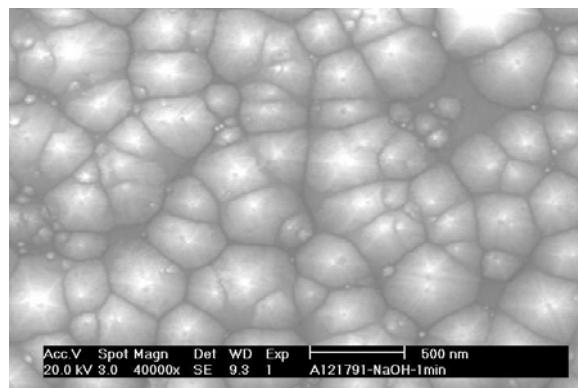


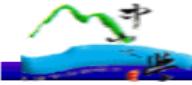
Buffer layer

- Unstable : N-polarity
 - LT-GaN
 - LT-AlN
 - HT-GaN
- Stable : Ga-polarity
 - HT-AlN

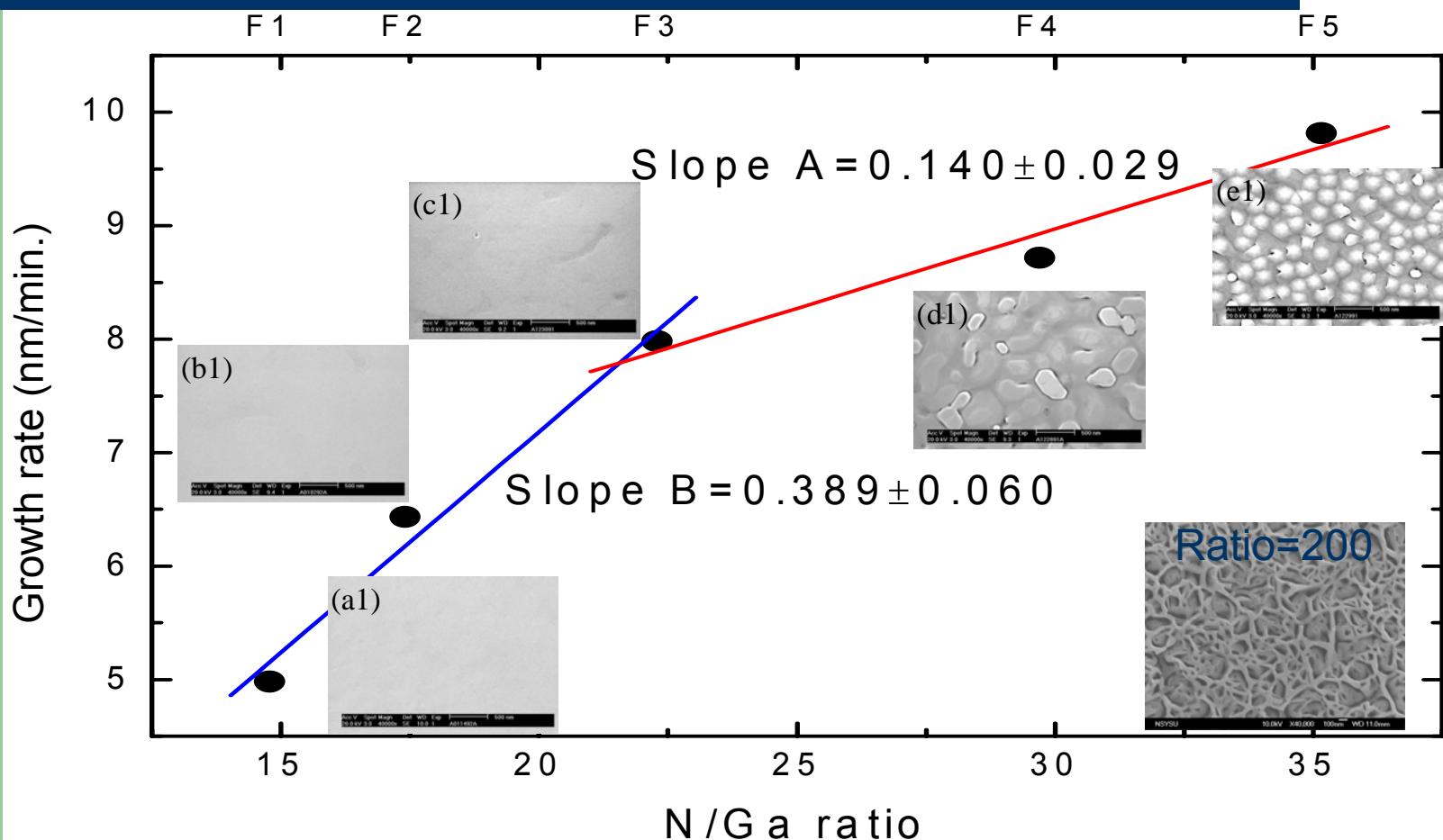


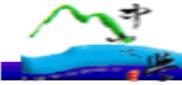
after chemical
wet etching
(NaOH)
→





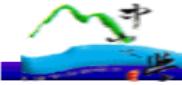
GaN epitaxy layer





Characteristic Measurements

1. Reflective high energy electron diffraction
2. Alpha step surface profiler
3. Field emission scanning electron microscopy
4. Transmission electron microscope
5. Atomic force microscope
6. Photoluminescence
7. Raman scattering
8. High resolution X-ray diffraction
9. Auger electron spectroscopy
10. Secondary ion mass spectrometry
11. Electron probe microanalyzer
12. Hall effect measurement
13. Shubnikov-de Haas effect and quantum Hall effect

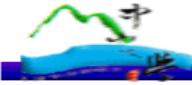


Hall effect measurement system

- Working conditions
 - Temperature:
Room temperature, 77 K
 - Magnetic field:
0~500 mT

- Results
 - Mobility
 - Carrier concentration



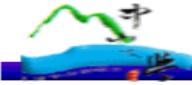


Low temperature and high magnetic field system I

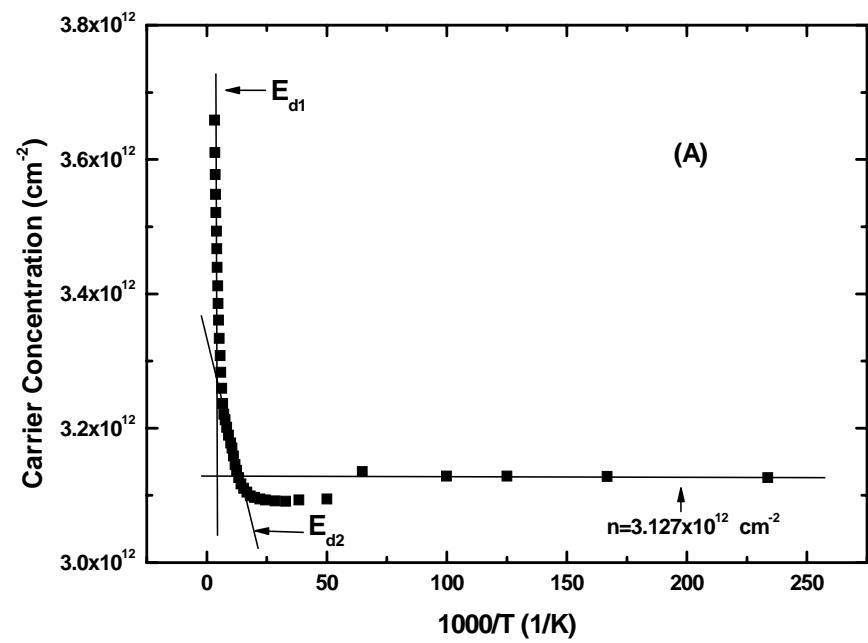
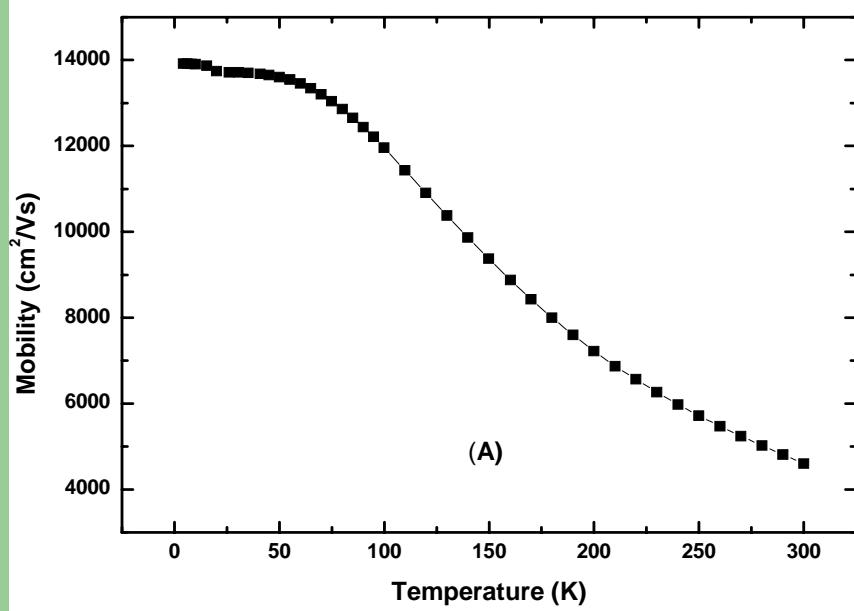
Lake Shore 9705

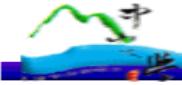
- Working conditions
 - Temperature:
2~400 K
 - Magnetic field:
0~5 T
- Results
 - Mobility
 - Carrier concentration





Low temperature and high magnetic field system I

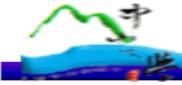




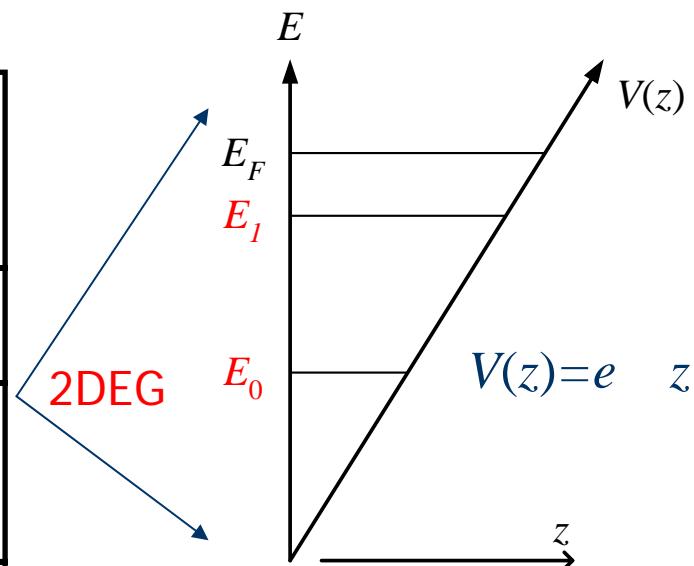
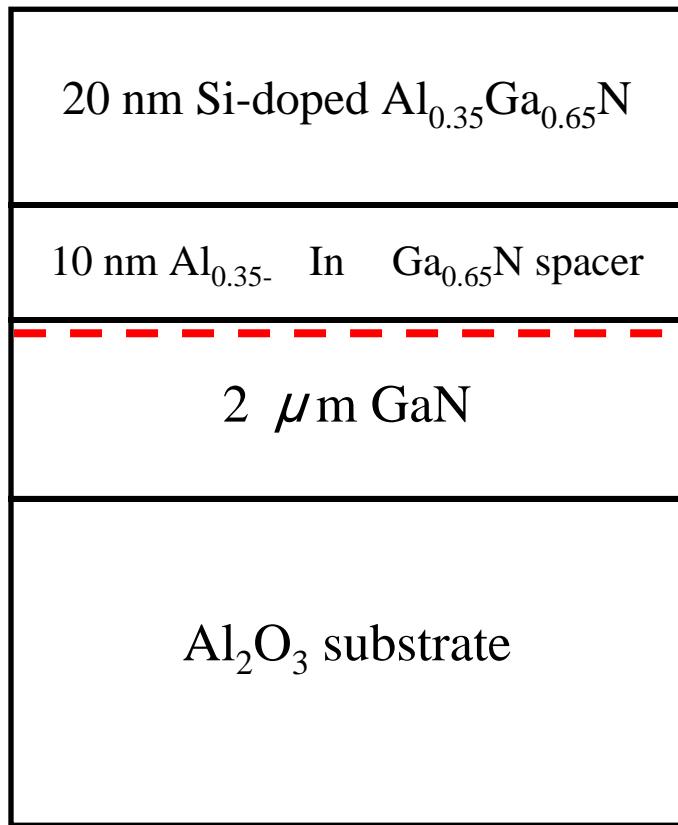
Low temperature and high magnetic field system II

- Working conditions
 - Temperature:
 - He⁴ system: RT~1.2 K
 - He³ system: RT~0.3 K
 - Dilution system: RT~0.03K
 - Magnetic field: 0~14 T
- Results
 - Shubnikov-de Haas
 - Quantum Hall Effect



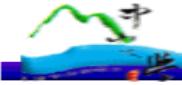


Piezoelectric effect on $\text{Al}_{0.35-\text{x}}\text{In}_x\text{Ga}_{0.65}\text{N}/\text{GaN}$ heterostructures



Si doping level of the top barrier
is the same, $5 \times 10^{18} \text{ cm}^{-3}$
Sample G1, $= 0$
Sample G2, $< 0.01\%$

For a triangular potential well confined by a electric field



Piezoelectric effect on Al_{0.35}-In_xGa_{0.65}N/GaN heterostructures

$$-\frac{\hbar^2}{2m^*} \frac{d^2}{dz^2} \psi(z) + e\xi z \psi(z) = E_i \psi(z)$$

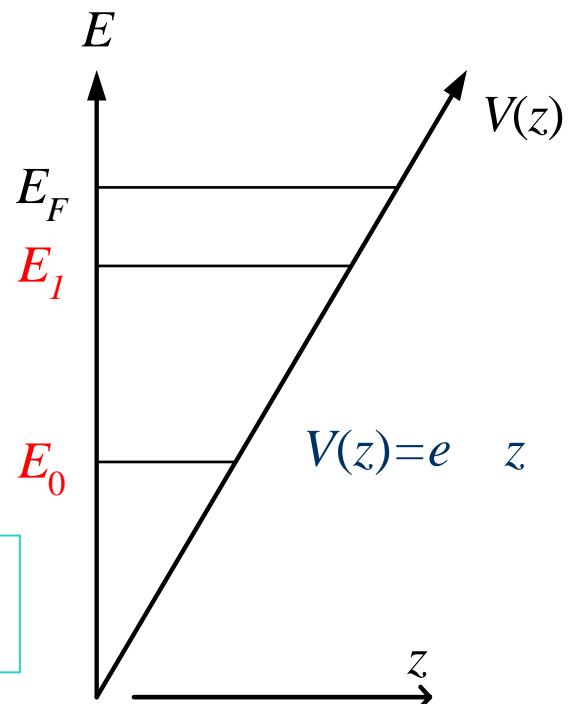
$$E_i = \left(\frac{\hbar^2}{2m^*} \right)^{\frac{1}{3}} \left(\frac{3\pi e \xi}{2} \right)^{\frac{2}{3}} \left(i + \frac{3}{4} \right)^{\frac{2}{3}}$$

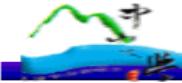
$$\Delta E_i = E_F - E_i = \frac{\pi \hbar^2 n_i}{m_i^*}$$

$$m^*(E) = m_b [1 + 2E/E_g] \sim 0.215 m_0$$

From SdH measurement

$$f_i = \frac{\hbar n_i}{2e}$$





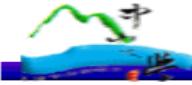
Piezoelectric effect on Al_{0.35}-In_xGa_{0.65}N/GaN heterostructures

$$\Delta E_{i-j} = \Delta E_i - \Delta E_j$$

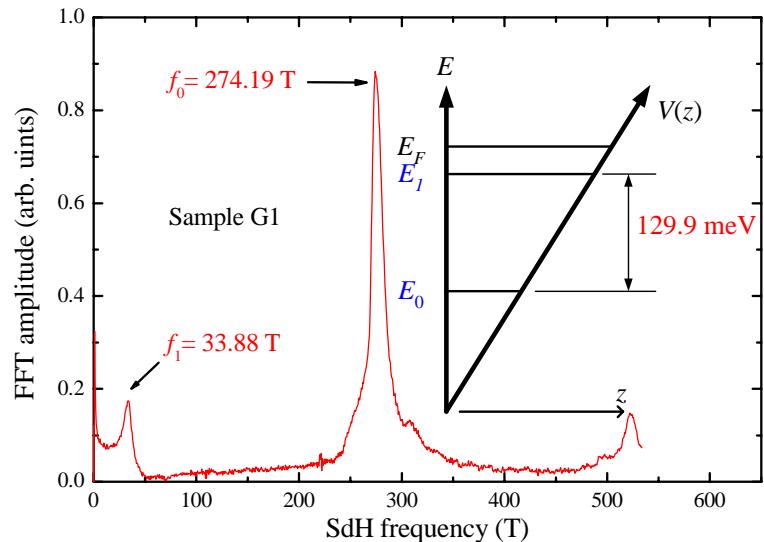
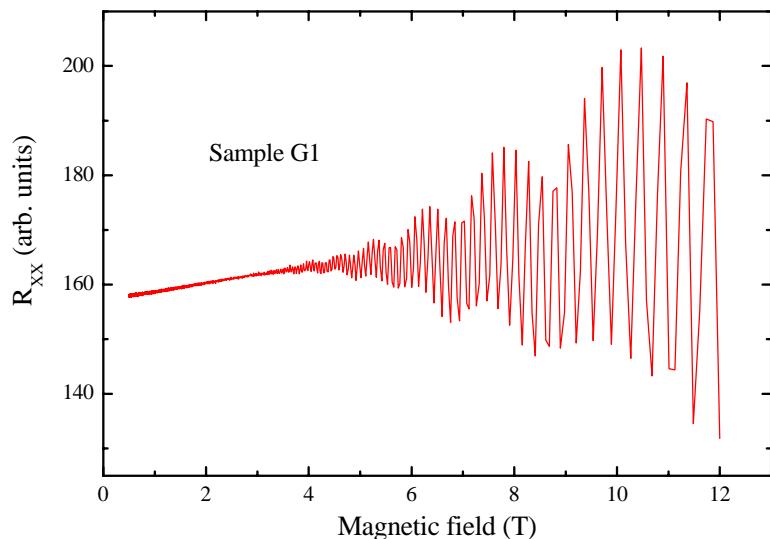
$$= (E_F - E_i) - (E_F - E_j) = E_j - E_i$$

$$= \left(\frac{\hbar^2}{2m^*} \right)^{\frac{1}{3}} \left(\frac{3\pi e \xi}{2} \right)^{\frac{2}{3}} \left[\left(\boxed{j} + \frac{3}{4} \right)^{\frac{2}{3}} - \left(\boxed{i} + \frac{3}{4} \right)^{\frac{2}{3}} \right]$$

$$\Delta E_{0-1} = \left(\frac{\hbar^2}{2m^*} \right)^{\frac{1}{3}} \left(\frac{3\pi e \xi}{2} \right)^{\frac{2}{3}} \left[\left(1 + \frac{3}{4} \right)^{\frac{2}{3}} - \left(0 + \frac{3}{4} \right)^{\frac{2}{3}} \right]$$



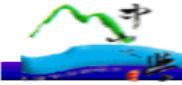
Piezoelectric effect on Al_{0.35}-In_xGa_{0.65}N/GaN heterostructures



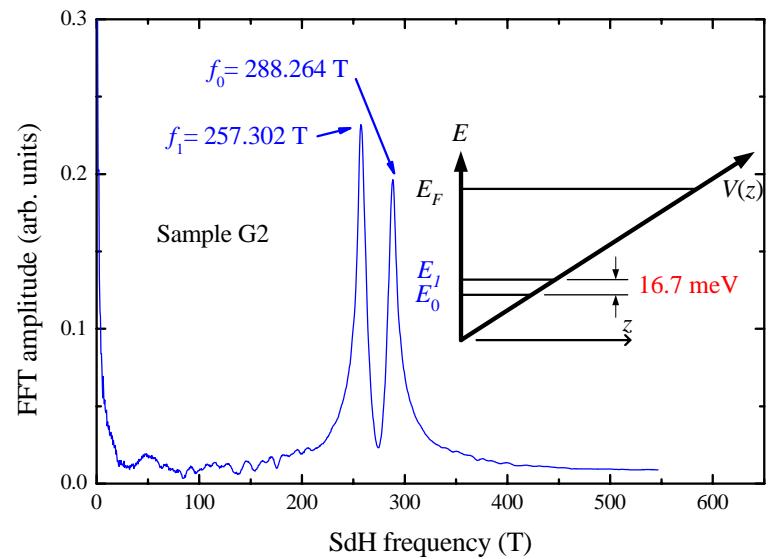
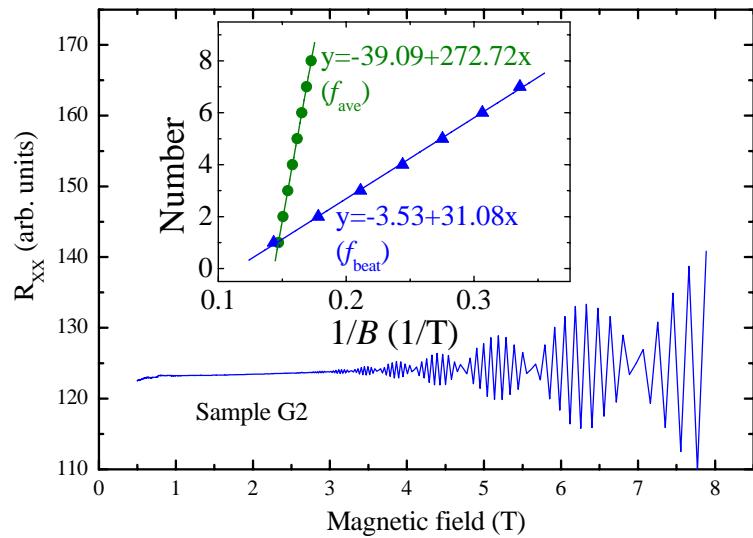
$$\begin{cases} f_0 = 274.19 \text{ T} \\ f_1 = 33.88 \text{ T} \end{cases} \rightarrow \begin{cases} n_0 = 1.330 \times 10^{13} \text{ cm}^{-2} \\ n_1 = 1.643 \times 10^{12} \text{ cm}^{-2} \end{cases}$$

$$\begin{cases} E_0 = 148.1 \text{ meV} \\ E_1 = 18.2 \text{ meV} \end{cases} \rightarrow E_{0-1} = 129.9 \text{ meV}$$

= 4.75×10⁵ V/cm



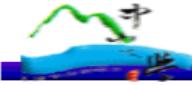
Piezoelectric effect on Al_{0.35}-In_xGa_{0.65}N/GaN heterostructures



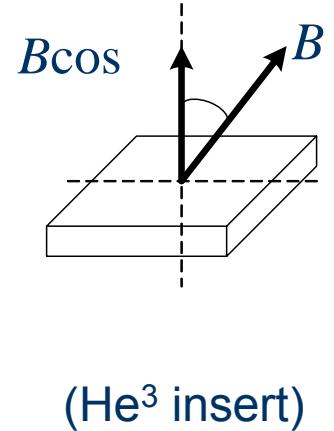
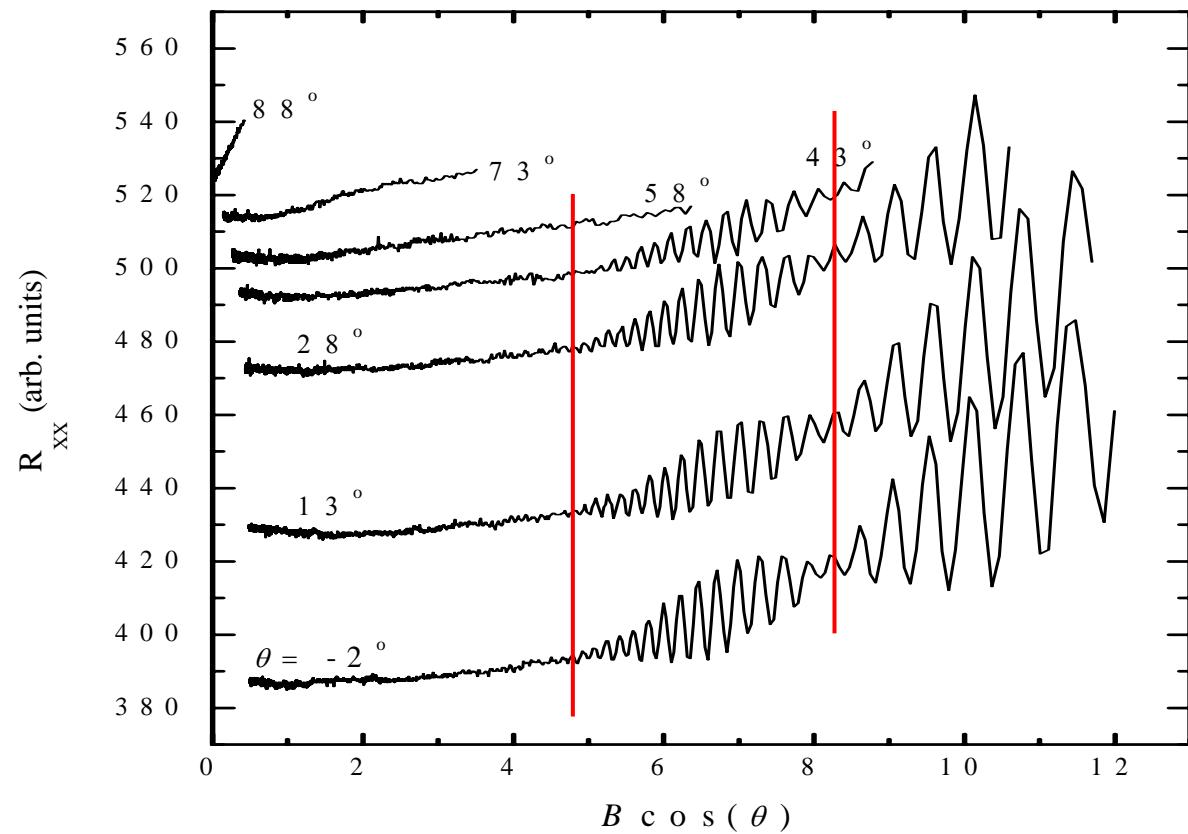
$$\begin{cases} f_0 = 288.26 \text{ T} \\ f_1 = 257.30 \text{ T} \end{cases} \rightarrow \begin{cases} n_0 = 1.398 \times 10^{13} \text{ cm}^{-2} \\ n_1 = 1.248 \times 10^{13} \text{ cm}^{-2} \end{cases}$$

$$\begin{cases} E_1 = 155.7 \text{ meV} \\ E_2 = 139.0 \text{ meV} \end{cases} \rightarrow E_{0-1} = 16.7 \text{ meV}$$

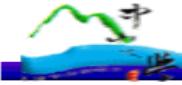
= **2.19×10⁴ V/cm**



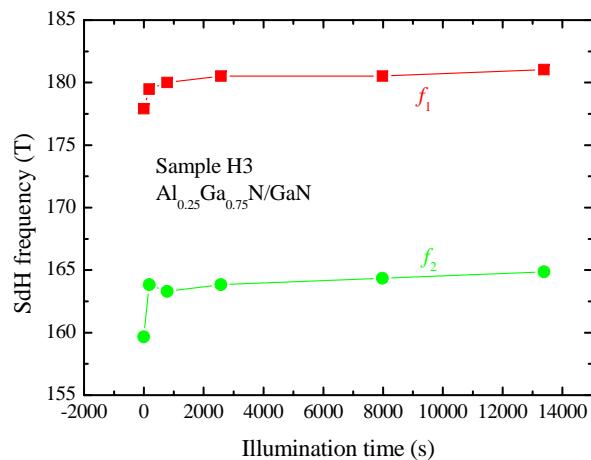
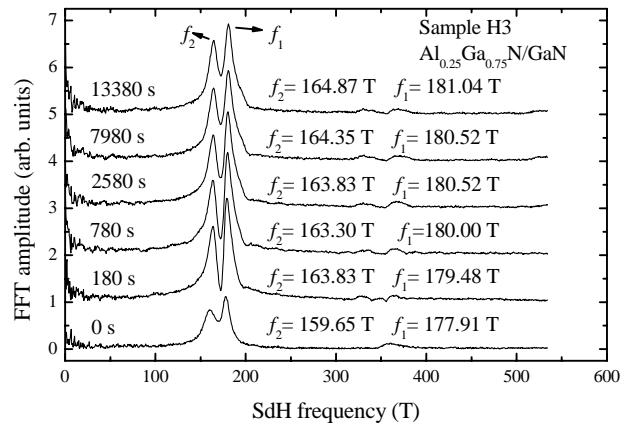
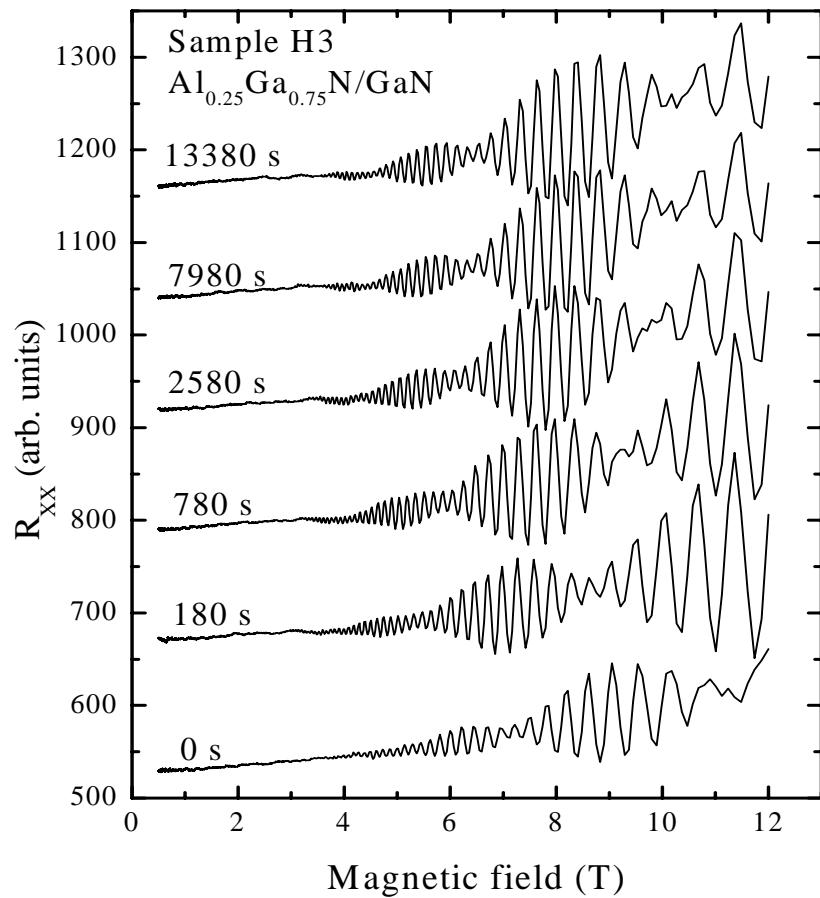
Other examples



(He³ insert)



Other examples

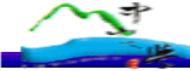




E-beam evaporation system

- Metal
 - Au
 - Al
 - Mo
 - W
 - Ti
 - Ni





Thanks for your attention.